

Final Product Change Notification

Issue Date: 12-Sep-2015
Effective Date: 25-Dec-2015

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For detailed information we invite you to view this notification online

201501001F01



Management Summary

- Capacity expansion PicoGate TSSOP-5 (SOT353) assembly lines at APM (NXP Semiconductors Assembly Plant Seremban Malaysia)

Seremban Malaysia)			
Change Category			
[] Wafer Fab process	[X] Assembly Process	[] Product Marking	[] Design
[] Wafer Fab materials	[X] Assembly Materials	[] Electrical spec./Test coverage	[] Mechanical Specification
[] Wafer Fab location	[] Assembly Location	[] Test Location	[] Packing/Shipping/Labeling
Expand assembly production capacity SOT353 package at APM (Assembly Plant Malaysia)			

Details of this Change

Expand assembly production capacity TSSOP-5 (SOT353) package at APM (NXP Semiconductors Assembly Plant Seremban Malaysia) by installation of state of the art production line

- Expansion of standard Strip to Strip production technology to include these packages
- No change in data sheet
- No assembly location change
- No test/packing location change
- No change in ordering part number / 12NC
- No change in product top side marking.

Why do we Implement this Change

- To support increased customer demand
- Order Lead-Time Improvement

Identification of Affected Products

- By date code
- No change in product top side marking

Product Availability

Sample Information

Samples are available upon request

Available in Logic sample store Nijmegen The Netherlands

Samples request for limited quantities can be made via sample store Nijmegen The Netherlands

Production

Planned first shipment 25-Dec-2015

Impact

No impact to the product's quality/functionality anticipated

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Not applicable additional capacity

Related Notifications

Notification Issue Date Effective DateTitle

201505005F0112-Sep- 25-Dec-2015 Phase 3: Expansion of industrial footprint for C075/C125 process

2015 74LVC/AVC/AUP (ASMC)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Oct-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Emile Busink

Position PCN specialist - QA engineering Logic Products

e-mail address emile.busink@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest

possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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High Tech Campus, 5656 AG Eindhoven, The Netherlands

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